

Film Capacitors

Metallized Polypropylene Film Capacitors (MKP)

Series/Type: B32774P ... B32778P

Date: June 2018

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Metallized polypropylene film capacitors (MKP)

B32774P ... B32778P

MKP DC Link - 125 °C series up to 50 μ F

Typical applications

- Frequency converters
- Industrial and high-end power supplies
- Automotive DC-DC and Compressor

Climatic

- Max. operating temperature: 125 °C (case)
- Climatic category (IEC 60068-1:2013): 40/110/56

Construction

- Dielectric: Polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Capacitance value up to 50 μF
- Good self-healing properties
- Over-voltage capability
- Low losses with high current capability
- High reliability
- RoHS-compatible
- AEC-Q200D compliant

Terminals

- Parallel wire leads, lead-free tinned
- 2-pin and 4-pin
- Standard lead lengths: 6 -1 mm

Marking

Manufacturer's logo and lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated DC voltage

Delivery mode

Bulk (untaped, lead length 6-1 mm)





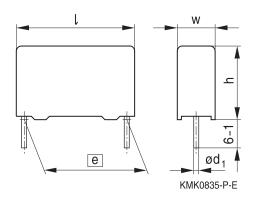
Dimensional drawings

Number of wires	Lead spacing e ±0.4	Lead diameter d ₁ ±0.05	Туре
2-pin	27.5	1.01)	B32774P
2-pin	37.5	1.0	B32776P
2-pin	37.5	1.01)	B32776P
4-pin	37.5	1.21)	B32776P
4-pin	52.5	1.21)	B32778P

Dimensions in mm

Dimensional drawings 2-pin versions

B32774P, B32776P

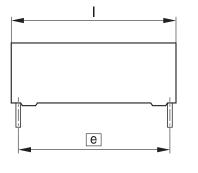


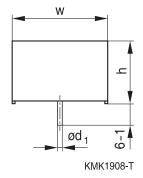


	B32774P	B32776P
Lead spacing e ±0.4:	27.5	37.5
Lead diameter d₁:	1.01)	1.0

Dimensions in mm

B32776P







Lead spacing @ ±0.4:	37.5
Lead diameter d ₁ :	1.01)

Dimensions in mm

1) Reinforced for vibration

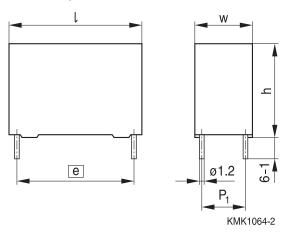




MKP DC Link - 125 $^{\circ}\text{C}$ series up to 50 μF

Dimensional drawings 4-pin versions

B32776P, B32778P





	B32776P	B32778P
Lead spacing <i>e</i> ±0.4:	37.5	52.5
Lead diameter d₁:	1.2 ²⁾	1.2 ²⁾

Dimensions in mm

²⁾ Reinforced for vibration







Overview of available types

Lead spacing	g 27.5 mm 37			37.5 m	37.5 mm			52.5 mm			
Туре	B32774	ŀΡ		B32776	B32776P			B32778P			
Page	6			7	7			8			
V _R (V DC)	630	700	840	630	700	840	630	700	840		
C _R (μF)											
1.0											
1.5											
2.0											
2.2											
2.7											
3.0											
3.3											
3.5											
3.9											
4.7											
5.0											
6.8											
7.0											
7.5											
8.0											
10											
12											
14											
15											
16											
20											
22											
25											
27											
30											
35											
40											
50											





B32774P

MKP DC link - high power series

Ordering codes and packing units (lead spacing 27.5 mm)

$C_R^{1)}$	Max. dimensions	Ordering code	I _{RMS,max} ²⁾	ESR _{typ}	ESL _{typ} ³⁾	$tan \delta$	tan δ	Un-
	$w \times h \times I$	(composition see below)	70 °C	70 °C		max.	max.	taped
			10 kHz	10 kHz		1 kHz	10 kHz	pcs./
μF	mm		Α	mΩ	nH	10 ⁻³	10 ⁻³	MOQ
$V_{R,85}$	° _C = 630 V DC							
1.5	$11.0 \times 19.0 \times 31.5$	B32774P6155+000	3.5	22.3	13.2	0.5	3.5	1280
2.2	$12.5 \times 21.5 \times 31.5$	B32774P6225+000	4.7	15.5	14.5	0.5	3.5	1120
3.0	$14.0 \times 24.5 \times 31.5$	B32774P6305+000	6.0	11.5	16.1	0.5	3.5	1040
4.7	$18.0 \times 27.5 \times 31.5$	B32774P6475+000	8.2	7.6	18.7	0.5	3.7	800
6.8	$21.0 \times 31.0 \times 31.5$	B32774P6685+000	10.4	5.4	21.3	0.6	3.9	720
8.0	$22.0 \times 36.5 \times 31.5$	B32774P6805+000	12.0	4.5	24.0	0.6	4.0	640
$V_{R,85}$	_{°C} = 700 V DC							
1.5	$11.0 \times 19.0 \times 31.5$	B32774P7155+000	3.6	20.3	18.4	0.5	3.2	1280
2.0	$12.5 \times 21.5 \times 31.5$	B32774P7205+000	4.7	15.3	19.8	0.5	3.2	1120
3.3	$18.0 \times 27.5 \times 31.5$	B32774P7335+000	7.3	9.6	22.9	0.5	3.3	800
4.7	$19.0 \times 30.0 \times 31.5$	B32774P7475+000	9.0	6.9	25.8	0.5	3.4	720
7.0	$22.0 \times 36.5 \times 31.5$	B32774P7705+000	11.8	5.0	31.2	0.5	3.7	640
$V_{R,85}$	_{°C} = 840 V DC							
1.0	$11.0 \times 19.0 \times 31.5$	B32774P8105+000	3.3	25.2	18.3	0.5	2.7	1280
1.5	$12.5 \times 21.5 \times 31.5$	B32774P8155+000	4.4	17.2	20.2	0.5	2.7	1120
3.0	$18.0 \times 27.5 \times 31.5$	B32774P8305+000	7.5	9.1	25.6	0.5	2.8	800
5.0	$22.0\times36.5\times31.5$	B32774P8505+000	12.5	5.8	31.6	0.5	3.0	640

MOQ = Minimum Order Quantity, consisting of 4 packing units. Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$ $J = \pm 5\%$ Packing code:

000 = untaped (lead length 6 - 1 mm)Other lead lengths available upon request

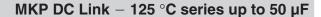
¹⁾ Capacitance value measured at 1 kHz

²⁾ Max. ripple current I_{RMS} at 85 °C at 10 kHz for a $\Delta T \leq \! 15$ °C when $\Delta ESR_{typ} \leq \! \pm \! 5\%$

³⁾ ESL value measured at resonance frequency (see specific graphs of Z versus frequency)



B32776P





Ordering codes and packing units (lead spacing 37.5 mm)

$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	$C_R^{1)}$	Max. dimensions	P ₁	Ordering code	I _{RMS,max} ²⁾	ESR _{typ}	ESL _{typ} ³⁾	tan δ	tan δ	Un-
		$w \times h \times l$		(composition see	85 °C			max.	max.	taped
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$				below)	10 kHz	10 kHz		1 kHz	10 kHz	pcs./
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	μF	mm	mm	,	Α	mΩ	nH	10 ⁻³	10 ⁻³	MOQ
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$V_{R,85}$	_{°C} = 630 V DC								
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	5.0	$24.0 \times 15.0 \times 42.0$	_	B32776P6505+000	6.0	13.4	19.4	0.9	6.9	1040
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	7.5	$24.0 \times 19.0 \times 42.0$	_	B32776P6755K000	7.6	9.5	19.6	0.9	6.9	780
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	10.0	$18.0 \times 32.5 \times 42.0$	_	B32776P6106K000	9.6	7.0	23.4	0.9	7.2	720
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	15.0	$20.0 \times 39.5 \times 42.0$	10.2	B32776P6156K000	13.0	4.8	12.4	0.9	7.1	640
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	20.0	$28.0 \times 37.0 \times 42.0$	10.2	B32776P6206K000	16.0	3.6	11.5	0.9	7.1	440
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	22.0	$28.0 \times 42.5 \times 42.0$	10.2	B32776P6226K000	17.5	3.2	13.2	0.9	7.3	440
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	25.0	$30.0 \times 45.0 \times 42.0$	20.3	B32776P6256+000	19.5	2.9	13.9	0.9	7.4	400
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	30.0	$33.0 \times 48.0 \times 42.0$	20.3	B32776P6306+000	22.5	2.4	15.1	0.9	7.6	180
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$V_{R,85}$	° _C = 700 V DC								
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	3.9	$24.0 \times 15.0 \times 42.0$	_	B32776P7395+000	5.6	15.3	19.2	8.0	6.2	1040
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	5.0	$24.0 \times 19.0 \times 42.0$	_	B32776P7505+000	6.8	12.1	19.1	0.8	6.3	780
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	12.0	$20.0 \times 39.5 \times 42.0$	10.2	B32776P7126K000	12.5	5.3	12.4	0.8	6.4	640
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	14.0	$28.0 \times 37.0 \times 42.0$	10.2	B32776P7146+000	14.5	4.4	11.3	0.8	6.4	440
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	16.0	$28.0 \times 42.5 \times 42.0$	10.2	B32776P7166+000	16.0	3.9	12.5	0.8	6.5	440
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	20.0	$30.0 \times 45.0 \times 42.0$	20.3	B32776P7206+000	19.0	3.2	13.5	0.8	6.6	400
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	22.0	$33.0 \times 48.0 \times 42.0$	20.3	B32776P7226+000	20.5	2.9	14.2	0.9	6.7	180
3.5 24.0 × 19.0 × 42.0 — B32776P8355+000 6.2 14.3 19.2 0.7 5.2 780 8.0 20.0 × 39.5 × 42.0 10.2 B32776P8805+000 11.0 6.3 12.4 0.7 5.3 640 10.0 28.0 × 37.0 × 42.0 10.2 B32776P8106+000 13.5 5.1 11.5 0.7 5.3 440 12.0 28.0 × 42.5 × 42.0 10.2 B32776P8126+000 15.0 4.4 12.8 0.7 5.4 440 14.0 30.0 × 45.0 × 42.0 20.3 B32776P8146+000 17.0 3.8 13.7 0.7 5.5 400	$V_{R,85}$	° _C = 840 V DC								
8.0 20.0 × 39.5 × 42.0 10.2 B32776P8805+000 11.0 6.3 12.4 0.7 5.3 640 10.0 28.0 × 37.0 × 42.0 10.2 B32776P8106+000 13.5 5.1 11.5 0.7 5.3 440 12.0 28.0 × 42.5 × 42.0 10.2 B32776P8126+000 15.0 4.4 12.8 0.7 5.4 440 14.0 30.0 × 45.0 × 42.0 20.3 B32776P8146+000 17.0 3.8 13.7 0.7 5.5 400	2.7	$24.0 \times 15.0 \times 42.0$	_	B32776P8275+000	5.2	18.6	19.2	0.7	5.2	1040
10.0 28.0 × 37.0 × 42.0 10.2 B32776P8106+000 13.5 5.1 11.5 0.7 5.3 440 12.0 28.0 × 42.5 × 42.0 10.2 B32776P8126+000 15.0 4.4 12.8 0.7 5.4 440 14.0 30.0 × 45.0 × 42.0 20.3 B32776P8146+000 17.0 3.8 13.7 0.7 5.5 400	3.5	$24.0 \times 19.0 \times 42.0$	_	B32776P8355+000	6.2	14.3	19.2	0.7	5.2	780
12.0 28.0 × 42.5 × 42.0 10.2 B32776P8126+000 15.0 4.4 12.8 0.7 5.4 440 14.0 30.0 × 45.0 × 42.0 20.3 B32776P8146+000 17.0 3.8 13.7 0.7 5.5 400	8.0	$20.0 \times 39.5 \times 42.0$	10.2	B32776P8805+000	11.0	6.3	12.4	0.7	5.3	640
14.0 30.0 × 45.0 × 42.0 20.3 B32776P8146+000 17.0 3.8 13.7 0.7 5.5 400	10.0	$28.0 \times 37.0 \times 42.0$	10.2	B32776P8106+000	13.5	5.1	11.5	0.7	5.3	440
	12.0	$28.0 \times 42.5 \times 42.0$	10.2	B32776P8126+000	15.0	4.4	12.8	0.7	5.4	440
16.0 33.0 × 48.0 × 42.0 20.3 B32776P8166+000 19.0 3.3 14.5 0.7 5.5 180	14.0	$30.0 \times 45.0 \times 42.0$	20.3	B32776P8146+000	17.0	3.8	13.7	0.7	5.5	400
	16.0	$33.0\times48.0\times42.0$	20.3	B32776P8166+000	19.0	3.3	14.5	0.7	5.5	180

MOQ = Minimum Order Quantity, consisting of 4 packing units. Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$

 $J = \pm 5\%$

Packing code:

000 = untaped (lead length 6 - 1 mm)Other lead lengths available upon request

¹⁾ Capacitance value measured at 1 kHz

²⁾ Max. ripple current I_{RMS} at 85 °C at 10 kHz for a $\Delta T \le$ 15 °C when $\Delta ESR_{typ} \le \pm 5\%$

³⁾ ESL value measured at resonance frequency (see specific graphs of Z versus frequency)





B32778P

MKP DC Link - 125 °C series up to 50 μF

Ordering codes and packing units (lead spacing 52.5 mm, P_1 = 20.3 mm)

$C_R^{1)}$	Max. dimensions	Ordering code	I _{RMS,max} ²⁾	ESR _{typ}	ESL _{typ} ³⁾	$tan \ \delta$	tan δ	Un-
	$w \times h \times l$	(composition see below)	85 °C			max.	max.	taped
			10 kHz	10 kHz		1 kHz	10 kHz	pcs./
μF	mm		Α	mΩ	nΗ	10-3	10 ⁻³	MOQ
V _{R,85} °c	c = 630 V DC							
35.0	$30.0\times45.0\times57.5$	B32778P6356+000	18.5	4.0	13.9	1.6	14.3	280
50.0	$35.0\times50.0\times57.5$	B32778P6506K000	23.5	2.9	16.0	1.6	14.8	108
V _{R,85} °c	c = 700 V DC							
30.0	$30.0\times45.0\times57.5$	B32778P7306+000	18.5	4.2	14.2	1.5	12.9	280
40.0	$35.0\times50.0\times57.5$	B32778P7406+000	22.5	3.2	15.9	1.5	13.2	108
V _{R,85} °c	c = 840 V DC							
20.0	$30.0\times45.0\times57.5$	B32778P8206+000	16.5	5.1	14.0	1.2	10.6	280
27.0	$35.0\times50.0\times57.5$	B32778P8276+000	20.5	3.9	15.7	1.3	10.8	108

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Intermediate capacitance values are available on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $K = \pm 10\%$

 $J = \pm 5\%$

Packing code:

000 = untaped (lead length 6 - 1 mm)

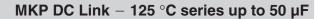
Other lead lengths available upon request

¹⁾ Capacitance value measured at 1 kHz

²⁾ Max. ripple current I_{RMS} at 85 °C at 10 kHz for a $\Delta T \leq \! 15$ °C when $\Delta ESR_{typ} \leq \! \pm \! 5\%$

³⁾ ESL value measured at resonance frequency (see specific graphs of Z versus frequency)







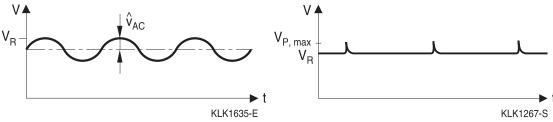
Technical data

Reference standard: IEC 60384-16:2005 and AEC-Q200D. All data given at T = 20 °C, unless otherwise specified.

otherwise specified.	
Rated temperature T _R	+85 °C
Operating temperature range (case)	Max. operating temperature, T _{op,max} +125 °C ¹⁾
	Upper category temperature T _{max} +110 °C
	Lower category temperature T_{min} $-40 ^{\circ}C$
Insulation resistance R _{ins} given as time	τ > 10000 s (after 1 min) at 500 V DC
constant $\tau = C_R \cdot R_{ins}$, rel. humidity $\leq 65\%$	
(minimum as-delivered values)	
DC voltage test between terminals (10 s)	1.5 · V _R
Voltage test terminal to case (10 s)	2110 V AC, 50 Hz
Peak current I _P (A)	C (μF) · dV/dt
V _R (V DC) at 85 °C¹)	630 700 840
Continuous operation voltage V _{op} at 105 °C¹)	540 600 720
Continuous operation voltage V _{op} at 125 °C¹)	450 500 600
For temperatures between 85 °C and 125 °C1)	0.7%/°C of V _{op} derating compared to V _{op} at 85 °C
Reliability:	
Failure rate λ	5 fit (≤ 1 · 10 ⁻⁹ h) at 0.5 · V _R , 40 °C
Service life t _{SL}	40 000 h at V _R , 85 °C
	For conversion to other operating conditions and
	temperatures, refer to chapter
	"Quality, 2 Reliability".

¹⁾ Temperatures given as operating temperature T_{op} (ambient temperature + self-heating), for example when ambient temperature is 125 °C, selfheating is 0 °C, or ripple current cannot be permitted.

Typical waveforms



Restrictions:

 V_R : Maximum operating peak voltage of either polarity but of a non-reversing waveform, for which the capacitor has been designed for continuous operation.





MKP DC Link - 125 °C series up to 50 μF

 $\boldsymbol{\hat{u}_{\text{AC}}} {\leq} \boldsymbol{0.2} \, \cdot \, \boldsymbol{V_{\text{R}}}$

 $V_{p,max}$:

Overvoltage	Maximum duration within one day
1.1 · V _R	30% of on-load duration
$1.15 \cdot V_R$	30 min.
$1.2 \cdot V_R$	5 min.
$1.3 \cdot V_R$	1 min.

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

Note:

The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor. These parameters are given for isolated pulses in such a way that the heat generated by one pulse will be completely dissipated before applying the next pulse. For a train of pulses, please refer to the curves of permissible AC voltage-current versus frequency.

dV/dt values

Lead spacing	27.5 mn	n		37.5 mn	n		52.5 mn	n	
Туре	B32774	Р		B32776	Р		B32778	Р	
V _R (V DC)	630	700	840	630	700	840	630	700	840
dV/dt in V/μs	50	75	100	35	54	73	25	35	50



B32774P

MKP DC link – high power series



Characteristics curves

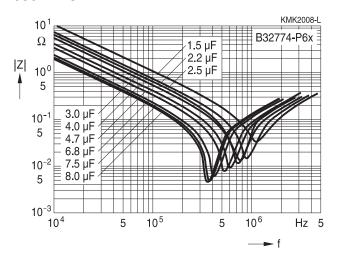
Additional technical information can be found under "Design support" on www.epcos.com.

Impedance Z versus frequency f

(typical values)

Lead spacing 27.5 mm

630 V DC

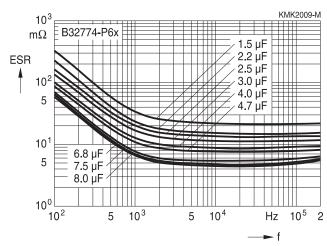


ESR versus frequency f

(typical values)

Lead spacing 27.5 mm

630 V DC

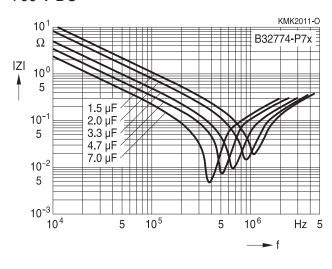


Impedance Z versus frequency f

(typical values)

Lead spacing 27.5 mm

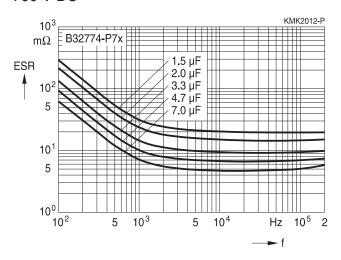
700 V DC



ESR versus frequency f

(typical values)

Lead spacing 27.5 mm







B32774P

MKP DC link - high power series

Characteristics curves

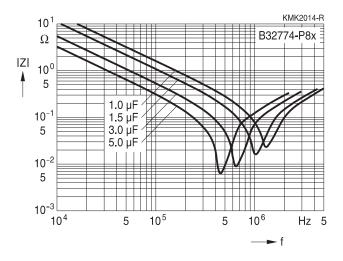
Additional technical information can be found under "Design support" on www.epcos.com.

Impedance Z versus frequency f

(typical values)

Lead spacing 27.5 mm

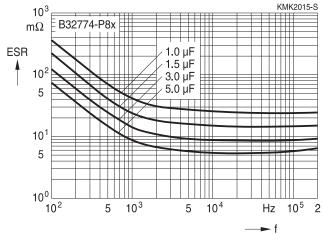
840 V DC



ESR versus frequency f

(typical values)

Lead spacing 27.5 mm





B32776P

MKP DC Link - 125 °C series up to 50 μ F



Characteristics curves

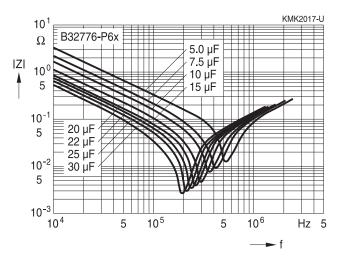
Additional technical information can be found under "Design support" on www.epcos.com.

Impedance Z versus frequency f

(typical values)

Lead spacing 37.5 mm

630 V DC

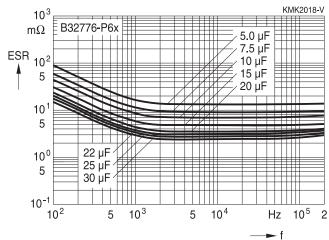


ESR versus frequency f

(typical values)

Lead spacing 37.5 mm

630 V DC

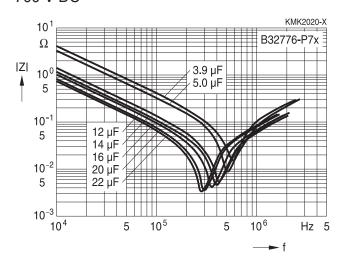


Impedance Z versus frequency f

(typical values)

Lead spacing 37.5 mm

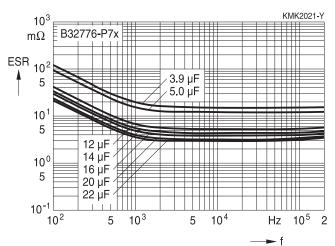
700 V DC



ESR versus frequency f

(typical values)

Lead spacing 37.5 mm







B32776P

MKP DC Link - 125 $^{\circ}$ C series up to 50 μ F

Characteristics curves

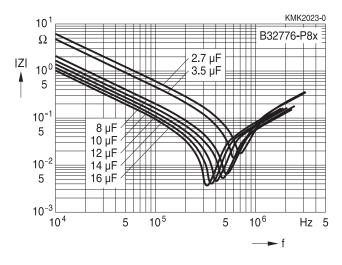
Additional technical information can be found under "Design support" on www.epcos.com.

Impedance Z versus frequency f

(typical values)

Lead spacing 37.5 mm

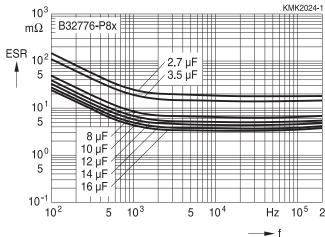
840 V DC



ESR versus frequency f

(typical values)

Lead spacing 37.5 mm





B32778P

MKP DC Link - 125 °C series up to 50 μ F



Characteristics curves

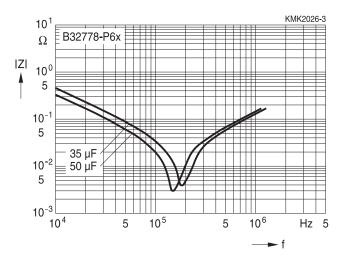
Additional technical information can be found under "Design support" on www.epcos.com.

Impedance Z versus frequency f

(typical values)

Lead spacing 52.5 mm

630 V DC

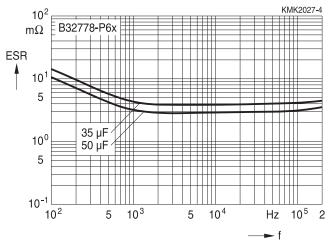


ESR versus frequency f

(typical values)

Lead spacing 52.5 mm

630 V DC

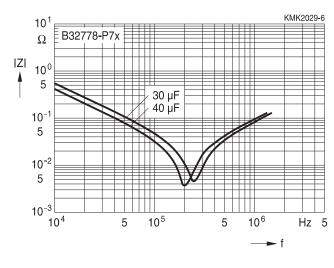


Impedance Z versus frequency f

(typical values)

Lead spacing 52.5 mm

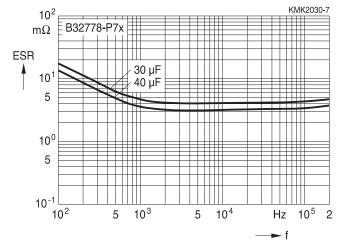
700 V DC



ESR versus frequency f

(typical values)

Lead spacing 52.5 mm







B32778P

MKP DC Link - 125 $^{\circ}$ C series up to 50 μ F

Characteristics curves

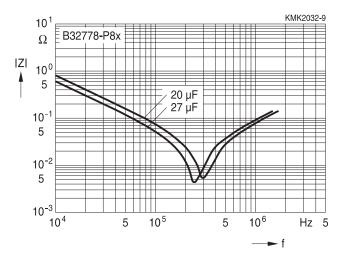
Additional technical information can be found under "Design support" on www.epcos.com.

Impedance Z versus frequency f

(typical values)

Lead spacing 52.5 mm

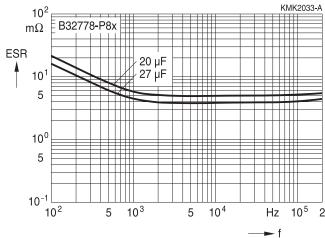
840 V DC



ESR versus frequency f

(typical values)

Lead spacing 52.5 mm





B32774P

MKP DC link – high power series



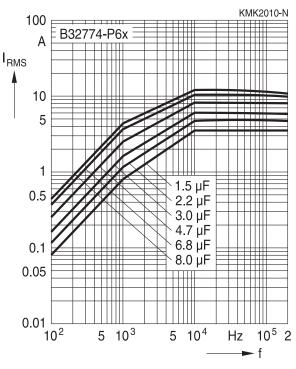
Characteristics curves

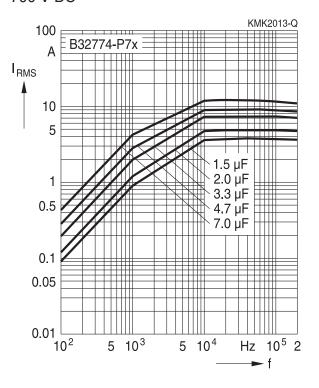
Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, T_A ≤85 °C)

For $T_A > 85$ $^{\circ}$ C, please use derating factor F_T .

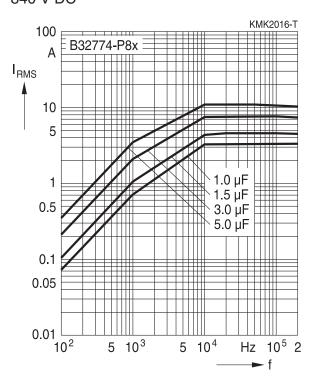
Lead spacing 27.5 mm

630 V DC





840 V DC







B32776P

MKP DC Link - 125 °C series up to 50 μ F

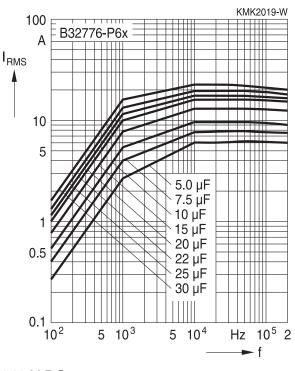
Characteristics curves

Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, T_A ≤85 °C)

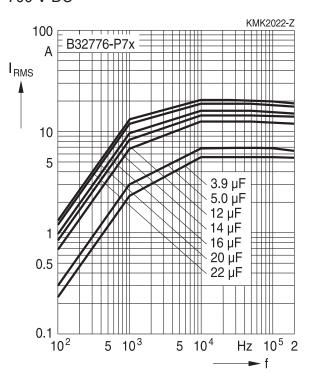
For $T_A > 85$ °C, please use derating factor F_T .

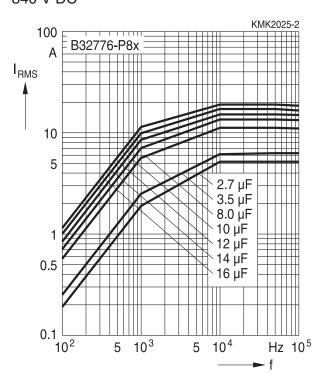
Lead spacing 37.5 mm

630 V DC



700 V DC







B32778P

MKP DC Link - 125 $^{\circ}$ C series up to 50 μ F



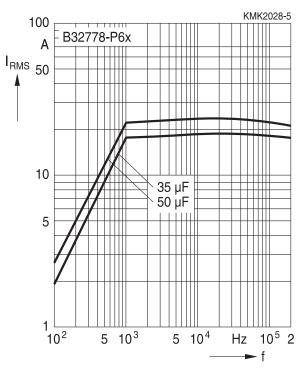
Characteristics curves

Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, T_A ≤85 °C)

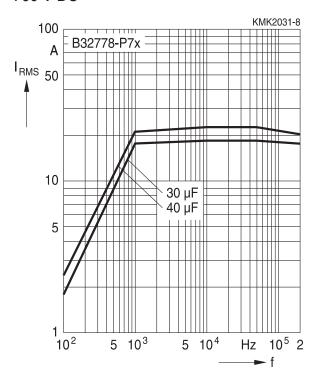
For $T_A > 85$ ${}^{\circ}C$, please use derating factor F_T .

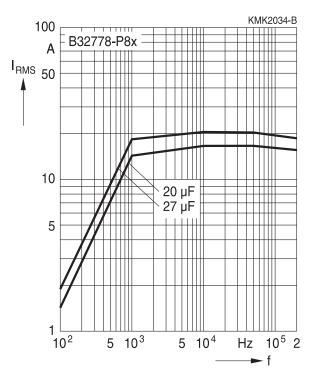
Lead spacing 52.5 mm

630 V DC



700 V DC



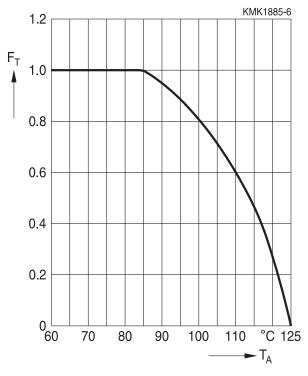






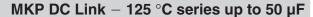
MKP DC Link - 125 $^{\circ}\text{C}$ series up to 50 μF

Curves characteristics (I_{RMS} derating versus temperature)



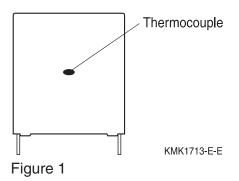
Maximum I_{RMS} current as function of the ambient temperature: I_{RMS} (T_A) = $F_T \times I_{RMS}$ (85 °C)







Heat transference for self heating calculation



Box dime	ensions	Equivalent heat coefficient	
w (mm)	h (mm)	I (mm)	G (mW/°C)
11.0	19.0	31.5	25
11.0	21.0	31.5	28
12.5	21.5	31.5	30
13.5	23.0	31.5	32
14.0	24.5	31.5	35
15.0	24.5	31.5	36
16.0	32.0	31.5	45
18.0	27.5	31.5	44
18.0	33.0	31.5	48
19.0	30.0	31.5	48
21.0	31.0	31.5	51
22.0	36.5	31.5	58
12.0	22.0	42.0	70
14.0	25.0	42.0	43
16.0	28.5	42.0	50
18.0	32.5	42.0	59
20.0	39.5	42.0	72
24.0	19.0	42.0	50
24.0	15.0	42.0	44
28.0	37.0	42.0	83
28.0	42.5	42.0	90
30.0	45.0	42.0	100
33.0	48.0	42.0	110
30.0	45.0	57.5	125
35.0	50.0	57.5	145

The equivalent heat coefficient "G (mW/°C)" is given for measuring the temperature on the lateral surface of the plastic box as figure 1 shows. By using a thermocouple and avoiding effect of radiation and convection the temperature measured during operation conditions should be a result of the dissipated power divided by the equivalent heat coefficient.





MKP DC Link - 125 $^{\circ}$ C series up to 50 μ F

Self heating by power dissipation and equivalent heat coefficient

The I_{RMS} and consequently the power dissipation must be limited during operation in order to not exceed the maximum limit of ΔT allowed for this series. ΔT_{max} given for this series is equal or lower than 15 °C at rated temperature (85 °C), for higher ambient temperatures ΔT_{max} (T) will have the same derating factor than I_{RMS} versus temperature and then an equivalent derating as per:

$$\Delta T_{\text{max}}$$
 (T) = (Factor)² × ΔT (85 °C).

For any particular I_{RMS} the ΔT may be calculated by:

$$\Delta T$$
 (°C) = P_{dis} (mW) / G(mW/°C).

Where ΔT (°C) is the difference between the temperature measured on the box (see figure 1) and the ambient temperature when capacitor is working during normal operation;

$$\Delta T$$
 (°C) = T_{op} (°C) - T_A (°C).

It represents the increasing of temperature provoked by the I_{RMS} during operation.

G (mW/°C) is the equivalent heat coefficient described above and P_{dis} (mW) is the dissipated power defined by: P_{dis} (mW) = ESR_{tvp} (m Ω) × I_{RMS}^2 (A_{RMS}).

Example for thermal calculation:

We will take as reference B32778P6506K (50 μ F/630 V DC) type for thermal calculation. Considering the following load and capacitor characteristics:

 I_{RMS} : 15 A_{RMS} at 20 kHz

T_A: 100 ^oC

 $35 \times 50 \times 57.5$ box

G (mW/ºC): 145

Then we have to find the ESR_{tvp} at 20 kHz what is approximately 2.9 m Ω .

So according to P_{dis} (mW) = ESR_{typ} (m Ω) × I_{RMS} ² (A_{RMS})

we have the following: P_{dis} (mW) = 2.9 m $\Omega \times 10$ A_{RMS}^2 = 290 mW.

And as per ΔT (°C) = P_{dis} (mW) / G (mW/°C)

we have the following: ΔT (°C) = 290 (mW) / 145 (mW/°C) = 2.0 °C.

What is below of the ΔT_{max} (100 °C) = (Factor)² × ΔT (85 °C) = (0.80)² × 15 °C = 9.6 °C.

On the other hand we may confirm that max I_{RMS} at 20 kHz at 85 °C = 23.5 A_{RMS} .

And then max I_{BMS} for 85 °C of ambient temperature is defined as follows:

$$I_{RMS}$$
 (100 °C) = Factor × I_{RMS} (85 °C) = 0.80 × 23.5 A_{RMS} = 18.8 A_{RMS} .

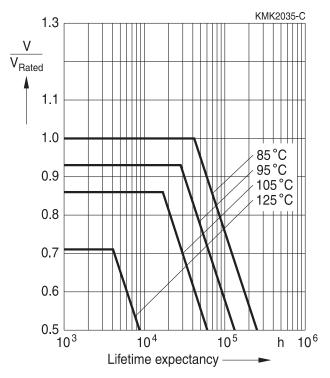
What confirms once again that I_{RMS} (10 A_{RMS} at 20 kHz at 100 °C) is below the max specified for such frequency and ambient temperature.







Service life Life time expectancy - typical curve



Note:

- (1) Confidence level of 98%
- (2) Life expectancy is given as a function of operating temperature (capacitor body temperature).





MKP DC Link - 125 $^{\circ}\text{C}$ series up to 50 μF

Testing and Standards

Test	Reference	Conditions of test		Performance requirements
Electrical para- meters (Routine test)	IEC61071:2007	Voltage between terminals, 1.5 V_R , during 10 s Insulation resistance, R_{ins} at 500 V Capacitance, C at 1 kHz (room temperature) Dissipation factor, tan δ at 1/10 kHz (room temperature)		Within specified limits
Robust- ness of termina- tions (Type test)	IEC 60068-2-21:2006	Tensile strength (test Wire diameter $0.5 < d_1 \le 0.8 \text{ mm}$ $0.8 < d_1 \le 1.25 \text{ mm}$	Ua1) Tensile force 10 N 20 N	Capacitance and tan δ within specified limits
Resistance to soldering heat (Type test)	IEC 60068-2-20:2008, test Tb, method 1A	Solder bath temperature at 260 ±5 °C, immersion for 10 seconds		$ \Delta C/C_0 \le 2\%$ $ \Delta \tan \delta \le 0.002$
Bump (Type test)	IEC 60384-16:2005	Test Eb: Total 4000 bumps with 390 m/s² mounted on PCB 6 ms duration		No visible damage $ \Delta C/C_0 \leq 2\%$ $ \Delta \tan \delta \leq 0.002$ $R_{ins} \geq 50\% \text{ of initial limit}$
Climatic sequence (Type test)	IEC 60384-16:2005	Dry heat Tb / 16 h Damp heat cyclic, 1st cycle +55 °C / 24 h / 95% 100% RH Cold Ta / 2 h Damp heat cyclic, 5 cycles +55 °C / 24 h / 95% 100% RH		No visible damage $ \Delta C/C_0 \leq 3\%$ $ \Delta \tan \delta \leq 0.001$ $R_{\text{ins}} \geq 50\% \text{ of initial limit}$
Thermal shock	AEC-Q200D	-55 °C +85 °C, 1000 cycles		No visible damage $ \Delta C/C_0 \leq 2\%$ $ \Delta \tan \delta \leq 0.002 \text{ (1kHz)}$ $R_{\text{ins}} \geq 50\% \text{ of initial limit}$
Vibration	AEC-Q200D	5 <i>g</i> for 20 minutes, 12 cycles, each of 3 orientations (X, Y, Z axis), 240 min/axis, total 12 hours Test from 10-2000 Hz		No visible damage





MKP DC Link - 125 °C series up to 50 μF

Test	Reference	Conditions of test	Performance requirements
Advanced humidity test	AEC-Q200D	40 °C / 93% RH / 1000 hours with V _R 60 °C / 95% RH / 500 hours with V _R	No visible damage $ \Delta C/C_0 \le 5\%$ $ \Delta \tan \delta/\tan \delta \le 400\%$ (1 kHz)
			$R_{ins} \ge 50\%$ of initial limit
		$V_R = 630$: $85 ^{\circ}\text{C} / 85\% \text{RH} / 1000 \text{hours with } 450 \text{V DC}$ $V_R = 700$: $85 ^{\circ}\text{C} / 85\% \text{RH} / 1000 \text{hours with } 500 \text{V DC}$	$\begin{split} \Delta C/C_0 &\leq 5\% \\ \Delta \ tan \ \delta &\leq 0.005 \ (1kHz) \\ R_{ins} &\geq 50\% \ of \ initial \ limit \end{split}$
		V _R = 840: 85 °C / 85% RH / 1000 hours with 600 V DC	
En- durance (Type test)	IEC 60384-16:2005	$85\ ^{\circ}\text{C}$ / 1.25 V_{R} / 1000 hours or 105 $^{\circ}\text{C}$ / 1.25 V_{op} / 1000 hours or 125 $^{\circ}\text{C}$ / 1.25 V_{op} / 1000 hours	No visible damage $\begin{split} \Delta C/C_0 &\leq 5\% \\ \Delta \tan \delta &\leq 0.005 \text{ (1 kHz)} \\ R_{\text{ins}} &\geq 50\% \text{ of initial limit} \end{split}$

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder



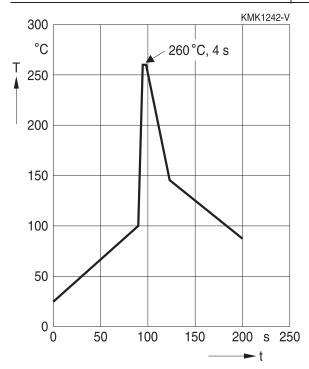


MKP DC Link - 125 $^{\circ}\text{C}$ series up to 50 μF

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1. Conditions:

Series		Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP			
MKP	(lead spacing >7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤7.5 mm)		<4 s
MKT	uncoated (lead spacing ≤10 mm) insulated (B32559)		recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane	
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between	
	capacitor body and liquid solder	
Evaluation criteria:		
Visual inspection	No visible damage	
$\Delta C/C_0$	2% for MKT/MKP/MFP	
$\Delta O/O_0$	5% for EMI suppression capacitors	
$tan \ \delta$	As specified in sectional specification	







1.3 General notes on soldering

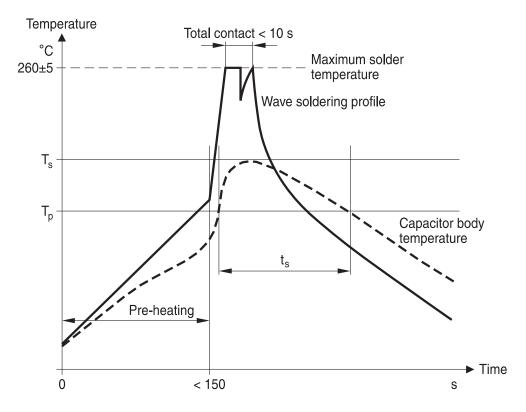
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



T_s: Capacitor body maximum temperature at wave soldering

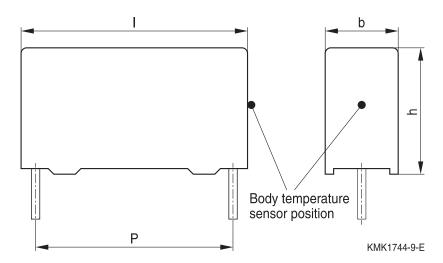
T_p: Capacitor body maximum temperature at pre-heating

KMK1745-A-E





MKP DC Link – 125 °C series up to 50 μF



Body temperature should follow the description below:

■ MKP capacitor

During pre-heating: T_p ≤110 °C

During soldering: T_s ≤120 °C, t_s ≤45 s

MKT capacitor

During pre-heating: T_p ≤125 °C

During soldering: T_s ≤160 °C, t_s ≤45 s

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be ≤ 120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be <360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Please refer to EPCOS Film Capacitor Data Book in case more details are needed.







Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of EPCOS.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage	Make sure that capacitors are stored within the specified	4.5
conditions	range of time, temperature and humidity conditions.	"Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive	5.3
	flammability), avoid overload of the capacitors (active	"Flammability"
	flammability) and consider the flammability of materials.	
Resistance to	Do not exceed the tested ability to withstand vibration.	5.2
vibration	The capacitors are tested to IEC 60068-2-6:2007.	"Resistance to
	EPCOS offers film capacitors specially designed for	vibration"
	operation under more severe vibration regimes such as	
	those found in automotive applications. Consult our	
	catalog "Film Capacitors for Automotive Electronics".	

Topic	Safety information	Reference chapter
		"Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits	1 "Soldering"
	during soldering.	
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"





MKP DC Link - 125 °C series up to 50 μF

Topic	Safety information	Reference chapter
		"Mounting guidelines"
Embedding of	When embedding finished circuit assemblies in plastic	3 "Embedding of
capacitors in	resins, chemical and thermal influences must be taken	capacitors in finished
finished	into account.	assemblies"
assemblies	Caution: Consult us first, if you also wish to embed other	
	uncoated component types!	

Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.







Symbols and terms

Symbol	English	German	
α	Heat transfer coefficient	Wärmeübergangszahl	
α_{C}	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität	
Α	Capacitor surface area	Kondensatoroberfläche	
β_{C}	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität	
С	Capacitance	Kapazität	
C_R	Rated capacitance	Nennkapazität	
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung	
ΔC/C	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)	
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	,	
dt	Time differential	Differentielle Zeit	
Δt	Time interval	Zeitintervall	
ΔΤ	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)	
∆tan δ	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors	
ΔV	Absolute voltage change	Absolute Spannungsänderung	
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)	
ΔV/Δt	Voltage change per time interval	Spannungsänderung pro Zeitintervall	
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion	
ESL	Self-inductance	Eigeninduktivität	
ESR	Equivalent series resistance	Ersatz-Serienwiderstand	
f	Frequency	Frequenz	
f ₁	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung	
f ₂	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung	
f _r	Resonant frequency	Resonanzfrequenz	
F_{D}	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion	
F _T	Derating factor	Deratingfaktor	
i	Current (peak)	Stromspitze	
I _C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)	





MKP DC Link - 125 $^{\circ}\text{C}$ series up to 50 μF

Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
i _z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
L _S	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R_{i}	Internal resistance	Innenwiderstand
R _{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_s	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_{s}	Series component of dissipation factor	Serienanteil des Verlustfaktors
T _A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T_{max}	Upper category temperature	Obere Kategorietemperatur
T _{min}	Lower category temperature	Untere Kategorietemperatur
t _{OL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
	and voltage	-spannung
T _{op}	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T _R	Rated temperature	Nenntemperatur
T _{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer





MKP DC Link - 125 $^{\circ}\text{C}$ series up to 50 μF

Symbol	English	German
V_{AC}	AC voltage	Wechselspannung
V_{C}	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_{i}	Input voltage	Eingangsspannung
V_{o}	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
ν̂ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V _{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



Important notes

The following applies to all products named in this publication:

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Important notes

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